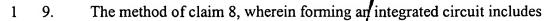
## What is claimed is:

- 1 1. A method of fabricating an integrated circuit that includes a
- 2 microelectromechanical (MEMS) device, comprising:
- forming a MEMS device on a substrate;
- 4 forming an integrated circuit; and
- 5 coupling the substrate to the integrated circuit to form a sealed cavity that
- 6 includes the MEMS device.
- 1 2. The method of claim 1, wherein coupling the substrate to the integrated
- 2 circuit includes coupling the substrate to a chip.
- 1 3. The method of claim 1 wherein forming a MEMS device on a substrate
- 2 includes forming a ring layer on the substrate that surrounds the MEMS device.
- 1 4. The method of claim 3, wherein coupling the substrate to the integrated
- 2 circuit includes bonding the ring layer to the integrated circuit.
- 1 5. The method of claim 3 wherein the ring layer is electrically conductive.
- 1 6. The method of claim 5, wherein forming a MEMS device on a substrate
- 2 includes depositing a wettable layer onto the ring layer.
- 1 7. The method of claim 3 wherein forming an integrated circuit includes
- 2 forming a ring layer on a surface of the integrated circuit.
- 1 8. The method of claim 7, wherein coupling the substrate to the integrated
- 2 circuit includes bonding the ring layer on the substrate to the ring layer on the
- 3 integrated circuit.

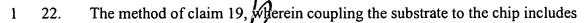


- 2 forming solder bumps within the ring layer on the substrate and forming a MEMS
- device on a substrate includes forming pads on the substrate, and coupling the
- 4 substrate to the integrated circuit includes bonding the pads on the substrate to the
- 5 solder bumps on the integrated circuit.
- 1 10. The method of claim 1, wherein forming an integrated circuit includes
- 2 forming a ring layer on the substrate.
- 1 11. The method of claim 10, wherein coupling the substrate to the integrated
- 2 circuit includes bonding the ring layer to the substrate.
- 1 12. The method of claim 1, wherein coupling the substrate to the integrated
- 2 circuit includes coupling the substrate to the integrated circuit in a controlled
- 3 environment.
- 1 13. The method according to claim 12, wherein coupling the substrate to the
- 2 integrated circuit in a controlled environment includes coupling the substrate to the
- 3 integrated circuit in a hermetic environment.
- 1 14. The method according to claim 12, wherein coupling the substrate to the
- 2 integrated circuit in a controlled environment includes coupling the substrate to the
- 3 integrated circuit in a vacuum.

A method of fabricating an integrated circuit that includes a 1 15. 2 microelectromechanical (MEMS) device, comprising: 3 forming a MEMS device on a substrate; forming a ring layer on the substrate that surrounds the MEMS device; 4 5 forming an integrated circuit; forming a ring layer on a surface of the integrated circuit; and 6 coupling the substrate to the integrated circuit by bonding the ring layer on 7 8 the substrate to the ring layer on the integrated circuit to form a sealed cavity that includes the MEMS device. 9 16. The method of claim 15, wherein coupling the substrate to the integrated 1 2 circuit includes coupling the substrate to a chip. The method of claim 15, wherein coupling the substrate to the integrated 1 17. circuit includes coupling the substrate to the integrated circuit in a controlled 2 3 environment. The method of claim 15, wherein the ring layers on the substrate and the 18. 1 2 integrated circuit are electrically conductive. 1 19. A method of forming a microelectromechanical (MEMS) device, 2 comprising: 3 forming a MEMS device on a substrate; and 4 coupling the substrate to a chip to form a sealed cavity that includes the 5 MEMS device. 20. The method of claim 19, wherein forming a MEMS device on a substrate 1 2 includes forming a ring layer on the substrate that surrounds the MEMS device. 1 21. The method of claim 20, wherein coupling the substrate to the chip includes bonding the ring layer on the substrate to the chip. 2

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- 2 coupling the substrate to the chip in a controlled environment such that sealed cavity
- 3 becomes a controlled environment.
- 1 23. An integrated circuit comprising:
- a body including a MEMS device mounted on a surface of the body, the
- body including a ring layer on the surface of the body that surrounds the MEMS
- 4 device; and
- a substrate bonded to the ring layer on the integrated circuit to seal the
- 6 MEMS device within a cavity defined by the body, the ring layer and the substrate.
- 1 24. The integrated circuit of claim 23, wherein the substrate is a chip.
- 1 25. The integrated circuit of claim 23, further comprising a wettable layer
- 2 deposited onto the ring layer.
- 1 26. The integrated circuit of claim 23, wherein the substrate includes a ring layer
- on a surface of the substrate that is bonded to the ring layer on the body.
- 1 27. The integrated circuit of claim 26, wherein the substrate includes solder
- 2 bumps within the ring layer on the substrate, and the body includes pads within the
- 3 ring layer on the body such that the pads are bonded to the solder bumps.
- 1 28. The integrated circuit of claim 26, wherein the ring layers on the substrate
- 2 and the integrated circuit are electrically conductive.

169 PS